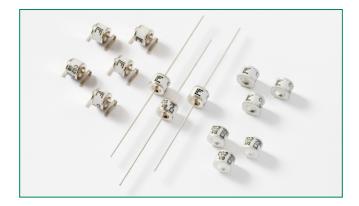


CG/CG2 Series









Agency Approvals

AGENCY	AGENCY FILE NUMBER		
71 °	E128662		
71	E320116 (CG2800 & CG21000 only)		

2 Electrode GDT Graphical Symbol



Description

Littelfuse highly reliable CG/CG2 Series GDTs provide a high degree of surge protection in a small size ideal for board level circuit protection.

GDTs function as switches which dissipate a minimum amount of energy and therefore handle currents that far surpass other types of transient voltage protection. Their gas-filled, rugged ceramic metal construction make them well suited to adverse environments.

The CG/CG2 series comes in a variety of forms including surface mount, core, straight and shaped leads, to serve a variety of mounting methods.

The CG Series (75-110V) is ideal for protection of test and communication equipment and other devices in which low voltage limits and extremely low arc voltages are required.

The CG2 Series (145V-1000V) is ideal for protecting equipment where higher voltage limits and holdover voltages are necessary.

Features

- Rugged Ceramic-Metal construction
- Low Capacitance (<1.5pf)
- Meets REA PE-80
- Available in surface mount, and a variety of lead options options

Applications

- Communication lines and equipment
- CATV equipment
- Test equipment
- Data lines
- Power supplies

- Instrumentation circuits
- Medical electronics
- ADSL equipment
- Telecom SLIC protection

Gas Discharge Tube (GDT) Products CG/CG2 Series

Electrical Characteristics

	Device Specifications (at 25°C)					Life Ratings										
Part		Breakd in Volts @100V/s	s	Impulse Break- down in Volts (@100V/µs)	Impulse Break- down In Volts (@1 Kv/µsec)	Insulation Resistance	Capaci- tance (@1MHz)	Arc Voltage (on state Voltage) @1Amp Min	Surge Life (@500A 10/1000µs)	Nominal Impulse Discharge Current (8/20µs)	Nominal AC Discharge Current (10x1sec @50-60Hz)	AC Dischage Current (9 cycle @50Hz)	DC Holdover Voltage ²	Max Impulse Discharge Current (1 Application @ 10/350µs)		
Number	MIN	TYP	MAX	MAX		MIN	MAX	TYP					TYP			
CG75	60	75	90	400	650											
CG90	72	90	108	400	600	10¹0 Ω							52 V	4kA		
CG90 SN	72	90	108	400	600	(at 50V)										
CG110	88	110	132	450	600											
CG2145	116	145	174	500	600								80 V			
CG2145 SN	120	145	174	500	600											
CG2230	195	230	265	600	700											
CG2230 SN	184	230	276	600	700		1.5 pf									
CG2250	213	250	288	625	725			5 pf 15 V	400 shots	10 shots (@20kA) ³	20 A	100 A		2.5kA		
CG2250 SN	200	250	300	625	725											
CG2300	255	300	345	700	800											
CG2300 SN	240	300	360	700	800	10¹0 Ω										
CG2350	297	350	403	750	900	(at 100V)	(at 100V)								2.010 (
CG2350 SN	280	350	420	750	900								135 V			
CG2420	357	420	483	800	1000											
CG2470	400	470	540	850	1200											
CG2470 SN	376	470	564	850	1200											
CG2600	510	600	690	1000	1400											
CG2600 SN	480	600	720	1000	1400											
CG2800 ¹	680	800	920	1200	1500					10 shots	10 A					
CG21000 ¹	850	1000	1150	1500	1600					(@10kA)	107	65 A				

NOTES:

Product Characteristics

Materials	LS, Axial: Device: Tin Plated 2–5 Microns Lead Wires: Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator Core: Device: Tin Plated 17.5 ± 12.5 Microns. Construction: Ceramic Insulator MS: Device: Dull Tin Plated 7–9 Microns Construction: Ceramic Insulator
Product Marking	LF Logo, Voltage and date code; Black in positive print

Glow to arc transition current	< 0.5Amps	
Glow Voltage	60-160 Volts	
Storage and Operational Temperature	-40 to +90	
Maximum Follow On Current ¹	230 Volts r.m.s, 200 Amps. (800V and 1000V devices tested to UL1449 3rd edition)	

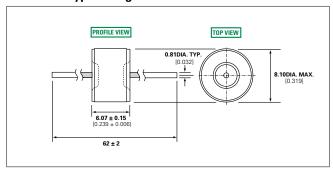
^{1.} Tested to UL1449

^{2.} Reference REA PE-80, 0.2A. Tested to ITU-T Rec K.12 and REA PE 80 < 150 mSec.

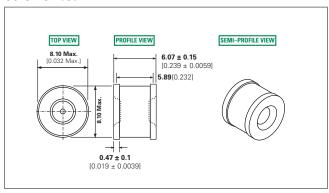


Device Dimensions

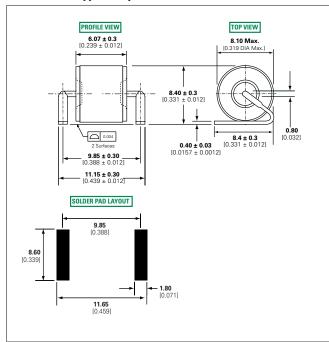
Leaded 'L' Type Straight Axial Devices



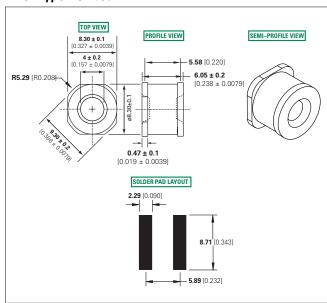
Core Devices



Leaded 'LS' Type Shaped Lead Devices



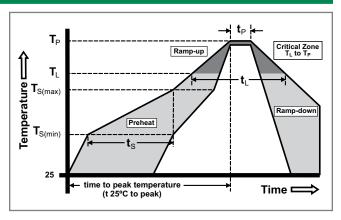
'MS' Type Devices



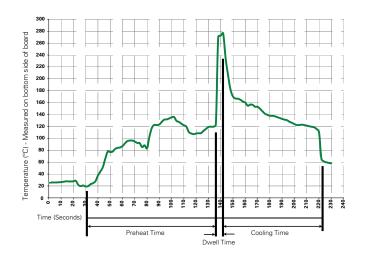


Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Co	ndition	Pb – Free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Pre Heat	-Temperature Max (T _{s(max)})	200°C		
	-Time (Min to Max) (t _s)	60 – 180 secs		
Average ra	amp up rate (Liquidus Temp k	3°C/second max		
T _{S(max)} to T _L	- Ramp-up Rate	5°C/second max		
Reflow	-Temperature (T _L) (Liquidus)	217°C		
	-Temperature (t _L)	60 – 150 seconds		
PeakTemp	erature (T _P)	260 ^{+0/-5} °C		
Time with Temperatu	in 5°C of actual peak ıre (t _p)	10 – 30 seconds		
Ramp-dov	vn Rate	6°C/second max		
Time 25°C	to peakTemperature (T _P)	8 minutes Max.		
Do not exc	ceed	260°C		



Soldering Parameters - Wave Soldering (Thru-Hole Devices)



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation		
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)		
Temperature Minimum:	100° C		
Temperature Maximum:	150° C		
Preheat Time:	60-180 seconds		
Solder Pot Temperature:	280° C Maximum		
Solder DwellTime:	2-5 seconds		

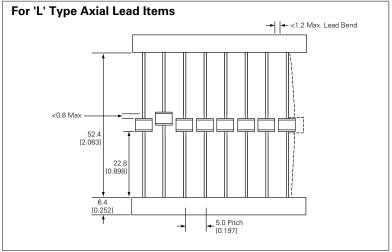
Soldering Parameters - Hand Soldering

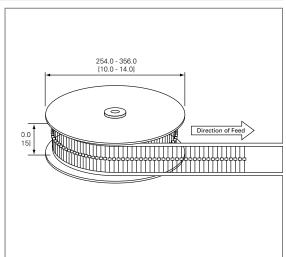
Solder Iron Temperature: 350° C +/- 5°C

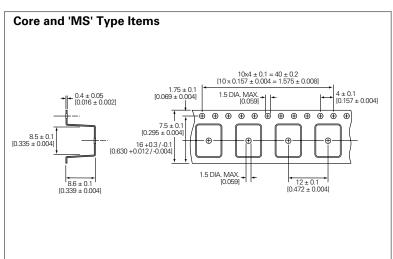
Heating Time: 5 seconds max.

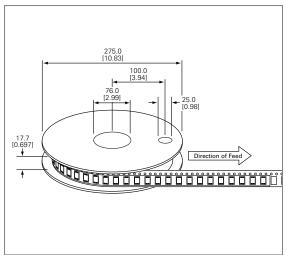


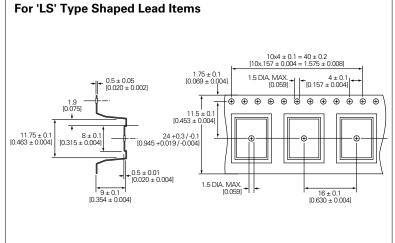
Packaging Dimensions

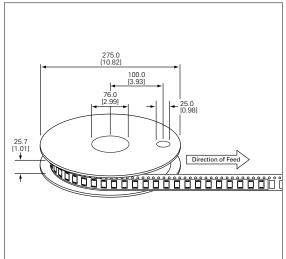






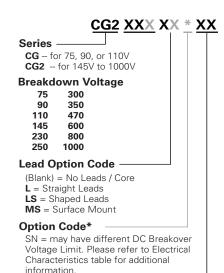






Gas Discharge Tube (GDT) Products CG/CG2 Series

Part Numbering System and Ordering Information



Examples:

CG75 - A non-leaded 75V device CG2230L -- A leaded 230V device

CG2800LTR - A leaded 800V device, tape-and-reel (per EIA standard RS-296-D)

Notes:

 ${\it CG/CG2}\ devices\ with\ other\ breakdown\ voltages\ in\ the\ 75\text{-}1000\ V\ range\ are\ available\ upon\ request.$

Packaging Option Code -

(Blank) = No Leads / Core, Bulk Bag - 400 pcs L(Blank) = Straight Lead, Tray - 50 pcs

LTR = Straight Lead, Tape & Reel per EIA RS-296-E - 500 per reel